

Copper Interconnect Technology

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Copper Interconnect Technology

**Christoph Steinbrüchel
Barry L. Chin**

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Arthur R. Weeks, Jr., Series Editor
Invivo Research Inc. and University of Central Florida



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Introduction to the Series

The Tutorial Texts series was initiated in 1989 as a way to make the material presented in SPIE short courses available to those who couldn't attend and to provide a reference book for those who could. Typically, short course notes are developed with the thought in mind that supporting material will be presented verbally to complement the notes, which are generally written in summary form, highlight key technical topics, and are not intended as stand-alone documents. Additionally, the figures, tables, and other graphically formatted information included with the notes require further explanation given in the instructor's lecture. As stand-alone documents, short course notes do not generally serve the student or reader well.

Many of the Tutorial Texts have thus started as short course notes subsequently expanded into books. The goal of the series is to provide readers with books that cover focused technical interest areas in a tutorial fashion. What separates the books in this series from other technical monographs and textbooks is the way in which the material is presented. Keeping in mind the tutorial nature of the series, many of the topics presented in these texts are followed by detailed examples that further explain the concepts presented. Many pictures and illustrations are included with each text, and where appropriate tabular reference data are also included.

To date, the texts published in this series have encompassed a wide range of topics, from geometrical optics to optical detectors to image processing. Each proposal is evaluated to determine the relevance of the proposed topic. This initial reviewing process has been very helpful to authors in identifying, early in the writing process, the need for additional material or other changes in approach that serve to strengthen the text. Once a manuscript is completed, it is peer reviewed to ensure that chapters communicate accurately the essential ingredients of the processes and technologies under discussion.

During the past nine years, my predecessor, Donald C. O'Shea, has done an excellent job in building the Tutorial Texts series, which now numbers nearly forty books. It has expanded to include not only texts developed by short course instructors but also those written by other topic experts. It is my goal to maintain the style and quality of books in the series, and to further expand the topic areas to include emerging as well as mature subjects in optics, photonics, and imaging.

*Arthur R. Weeks, Jr.
Invivo Research Inc. and University of Central Florida*

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